Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.025”**

**.025”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: E = .006 x .009 B = .004” X .005”**

**Backside Potential: COLLECTOR**

**APPROVED BY: DK DIE SIZE .025” X .025” DATE: 2/28/23**

**MFG: ZETEX THICKNESS .006” P/N: MPSA43**

**DG 10.1.2**

#### Rev B, 7/1